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### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Not For New Designs
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	SIO, SSU, UART/USART
Peripherals	LED, POR, Voltage Detect, WDT
Number of I/O	13
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 4x10b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-LSSOP (0.173", 4.40mm Width)
Supplier Device Package	20-LSSOP
Purchase URL	<a href="https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f21152sp-u0">https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f21152sp-u0</a>

## 1. Overview

This MCU is built using the high-performance silicon gate CMOS process using a R8C/Tiny Series CPU core and is packaged in a 20-pin plastic molded LSSOP. This MCU operates using sophisticated instructions featuring a high level of instruction efficiency. With 1 Mbyte of address space, it is capable of executing instructions at high speed.

Furthermore, the data flash ROM (1KB × 2blocks) is embedded in the R8C/15 group.

The difference between R8C/14 and R8C/15 groups is only the existence of the data flash ROM. Their peripheral functions are the same.

### 1.1 Applications

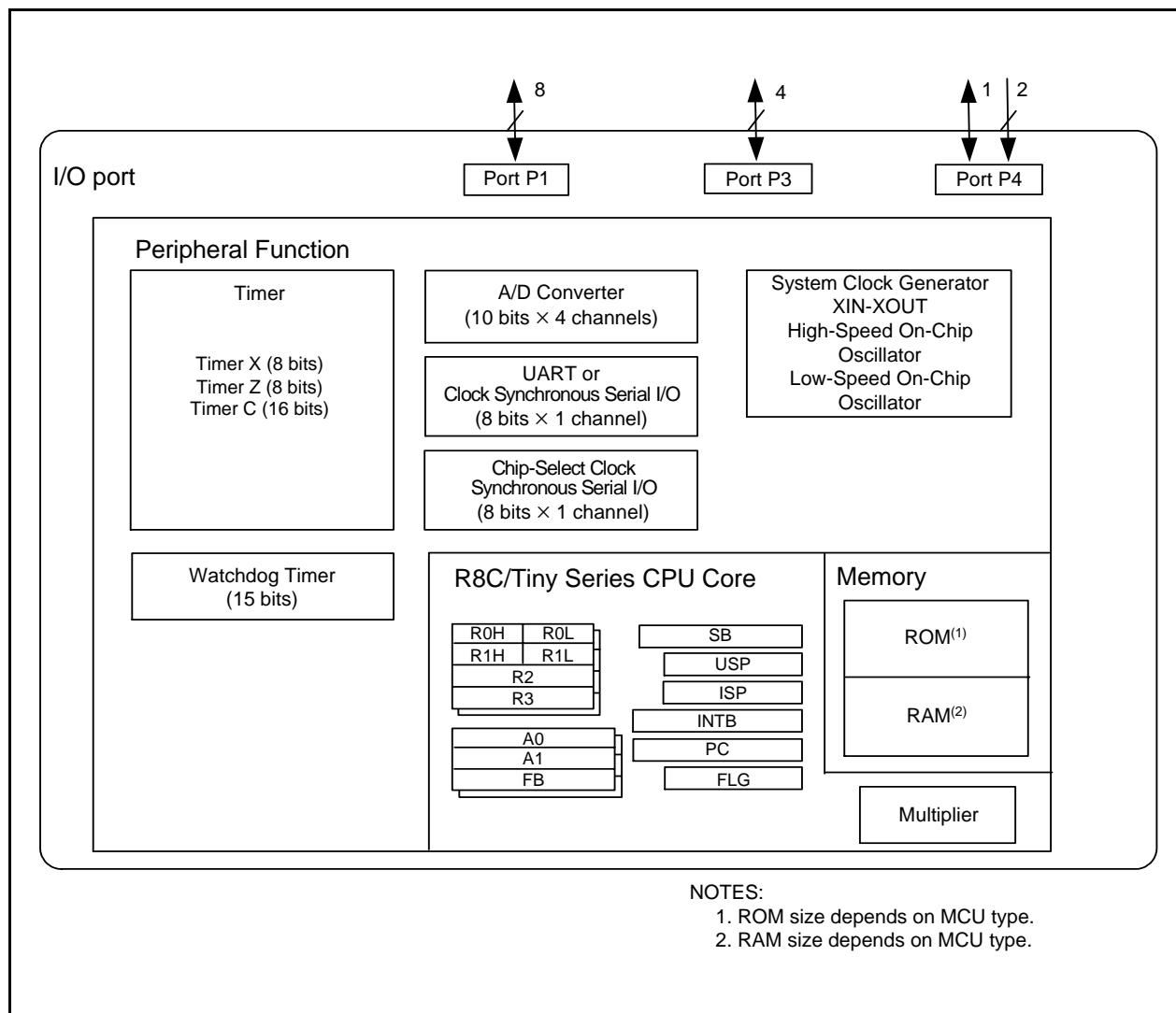
Electric household appliance, office equipment, housing equipment (sensor, security), general industrial equipment, audio, etc.

**Table 1.2 Performance Outline of the R8C/15 Group**

Item		Performance
CPU	Number of Basic Instructions	89 instructions
	Minimum Instruction Execution Time	50ns (f(XIN)=20MHz, VCC=3.0 to 5.5V) 100ns (f(XIN)=10MHz, VCC=2.7 to 5.5V)
	Operating Mode	Single-chip
	Memory Space	1 Mbyte
	Memory Capacity	See <b>Table 1.4 R8C/15 Group Product Information</b>
Peripheral Function	Port	I/O : 13 pins (including LED drive port), Input : 2 pins
	LED drive port	I/O port: 4 pins
	Timer	Timer X: 8 bits × 1 channel, Timer Z: 8 bits × 1 channel (Each timer equipped with 8-bit prescaler) Timer C: 16 bits × 1 channel (Circuits of input capture and output compare)
	Serial Interface	1 channel Clock synchronous serial I/O, UART
	Chip-select clock synchronous serial I/O (SSU)	1 channel
	A/D Converter	10-bit A/D converter: 1 circuit, 4 channels
	Watchdog Timer	15 bits × 1 channel (with prescaler) Reset start selectable, Count source protection mode
	Interrupt	Internal: 9 factors, External: 4 factors, Software: 4 factors Priority level: 7 levels
	Clock Generation Circuit	2 circuits • Main clock generation circuit (Equipped with a built-in feedback resistor) • On-chip oscillator (high speed, low speed) Equipped with frequency adjustment function on high-speed on-chip oscillator
	Oscillation Stop Detection Function	Main clock oscillation stop detection function
	Voltage Detection Circuit	Included
	Power on Reset Circuit	Included
Electric Characteristics	Supply Voltage	VCC=3.0 to 5.5V (f(XIN)=20MHz) VCC=2.7 to 5.5V (f(XIN)=10MHz)
	Power Consumption	Typ. 9mA (VCC=5.0V, f(XIN)=20MHz) Typ. 5mA (VCC=3.0V, f(XIN)=10MHz) Typ. 35μA (VCC=3.0V, wait mode, peripheral clock off) Typ. 0.7μA (VCC=3.0V, stop mode)
Flash Memory	Program/Erase Supply Voltage	VCC=2.7 to 5.5V
	Program/Erase Endurance	10,000 times (Data flash) 1,000 times (Program ROM)
Operating Ambient Temperature		-20 to 85°C -40 to 85°C (D Version)
Package		20-pin plastic mold LSSOP

### 1.3 Block Diagram

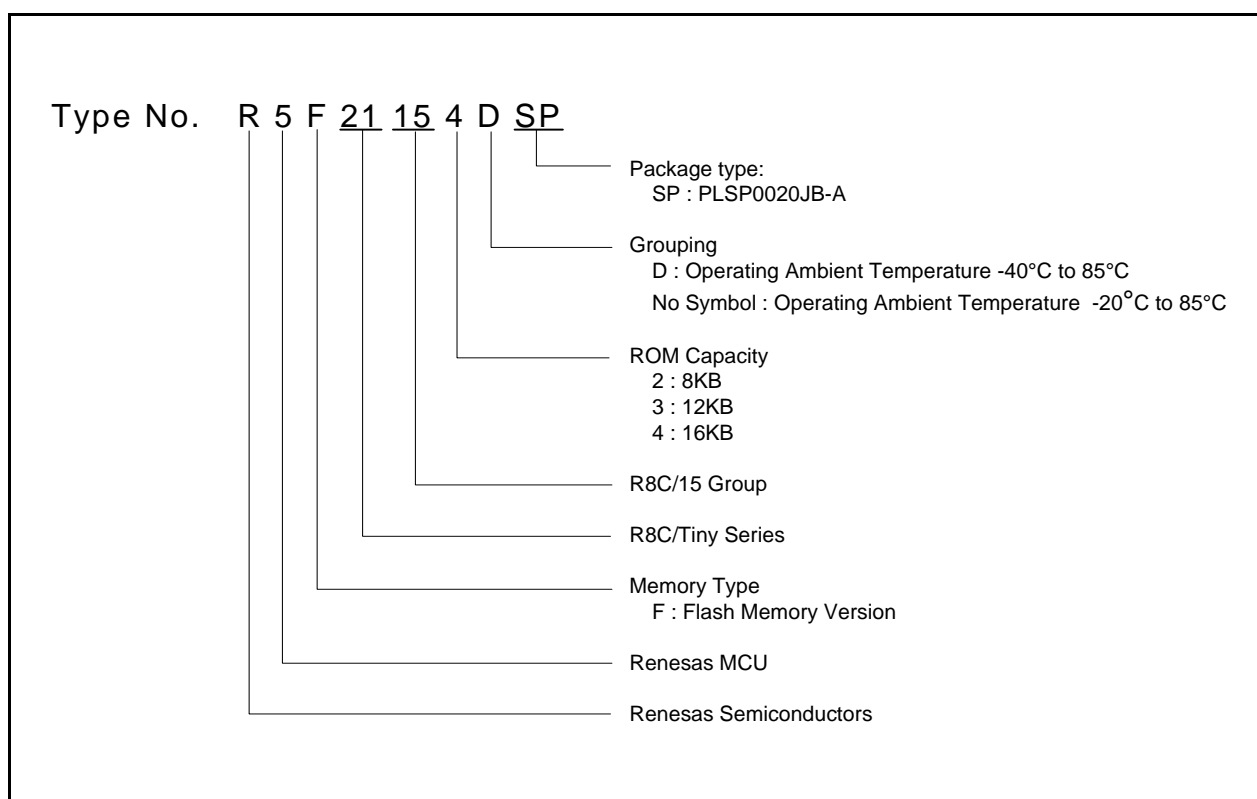
Figure 1.1 shows a Block Diagram.



**Figure 1.1 Block Diagram**

**Table 1.4 Product Information of R8C/15 Group****As of Jan 2006**

Type No.	ROM capacity		RAM capacity	Package type	Remarks
	Program ROM	Data flash			
R5F21152SP	8 Kbytes	1 Kbyte × 2	512 bytes	PLSP0020JB-A	Flash memory version  D version
R5F21153SP	12 Kbytes	1 Kbyte × 2	768 bytes	PLSP0020JB-A	
R5F21154SP	16 Kbytes	1 Kbyte × 2	1 Kbyte	PLSP0020JB-A	
R5F21152DSP	8 Kbytes	1 Kbyte × 2	512 bytes	PLSP0020JB-A	
R5F21153DSP	12 Kbytes	1 Kbyte × 2	768 bytes	PLSP0020JB-A	
R5F21154DSP	16 Kbytes	1 Kbyte × 2	1 Kbyte	PLSP0020JB-A	

**Figure 1.3 Part Number, Memory Size and Package of R8C/15 Group**

## 1.5 Pin Assignments

Figure 1.4 shows the PLSP0020JB-A Package Pin Assignment (top view).

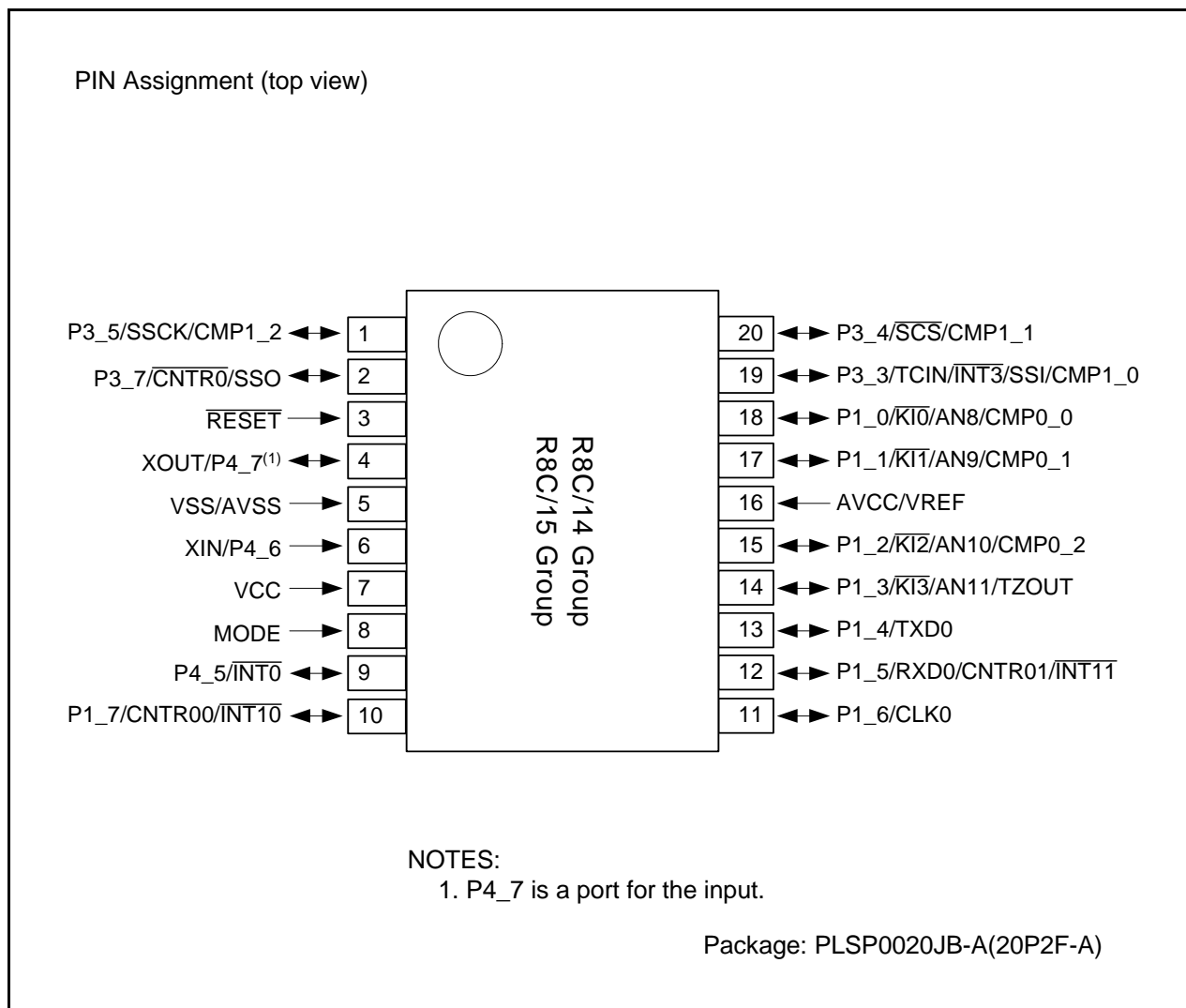


Figure 1.4 PLSP0020JB-A Package Pin Assignment (top view)

## 2.1 Data Registers (R0, R1, R2 and R3)

R0 is a 16-bit register for transfer, arithmetic and logic operations. The same applies to R1 to R3. The R0 can be split into high-order bit (R0H) and low-order bit (R0L) to be used separately as 8-bit data registers. The same applies to R1H and R1L as R0H and R0L. R2 can be combined with R0 to be used as a 32-bit data register (R2R0). The same applies to R3R1 as R2R0.

## 2.2 Address Registers (A0 and A1)

A0 is a 16-bit register for address register indirect addressing and address register relative addressing. They also are used for transfer, arithmetic and logic operations. The same applies to A1 as A0. A0 can be combined with A0 to be used as a 32-bit address register (A1A0).

## 2.3 Frame Base Register (FB)

FB is a 16-bit register for FB relative addressing.

## 2.4 Interrupt Table Register (INTB)

INTB is a 20-bit register indicates the start address of an interrupt vector table.

## 2.5 Program Counter (PC)

PC, 20 bits wide, indicates the address of an instruction to be executed.

## 2.6 User Stack Pointer (USP) and Interrupt Stack Pointer (ISP)

The stack pointer (SP), USP and ISP, are 16 bits wide each. The U flag of FLG is used to switch between USP and ISP.

## 2.7 Static Base Register (SB)

SB is a 16-bit register for SB relative addressing.

## 2.8 Flag Register (FLG)

FLG is a 11-bit register indicating the CPU state.

### 2.8.1 Carry Flag (C)

The C flag retains a carry, borrow, or shift-out bit that has occurred in the arithmetic logic unit.

### 2.8.2 Debug Flag (D)

The D flag is for debug only. Set to "0".

### 2.8.3 Zero Flag (Z)

The Z flag is set to "1" when an arithmetic operation resulted in 0; otherwise, "0".

### 2.8.4 Sign Flag (S)

The S flag is set to "1" when an arithmetic operation resulted in a negative value; otherwise, "0".

### 2.8.5 Register Bank Select Flag (B)

The register bank 0 is selected when the B flag is "0". The register bank 1 is selected when this flag is set to "1".

### 2.8.6 Overflow Flag (O)

The O flag is set to "1" when the operation resulted in an overflow; otherwise, "0".

### **2.8.7 Interrupt Enable Flag (I Flag)**

The I flag enables a maskable interrupt.

An interrupt is disabled when the I flag is set to "0", and are enabled when the I flag is set to "1". The I flag is set to "0" when an interrupt request is acknowledged.

### **2.8.8 Stack Pointer Select Flag (U Flag)**

ISP is selected when the U flag is set to "0", USP is selected when the U flag is set to "1".

The U flag is set to "0" when a hardware interrupt request is acknowledged or the INT instruction of software interrupt numbers 0 to 31 is executed.

### **2.8.9 Processor Interrupt Priority Level (IPL)**

IPL, 3 bits wide, assigns processor interrupt priority levels from level 0 to level 7.

If a requested interrupt has greater priority than IPL, the interrupt is enabled.

### **2.8.10 Reserved Bit**

When write to this bit, set to "0". When read, its content is indeterminate.



### 3. Memory

#### 3.1 R8C/14 Group

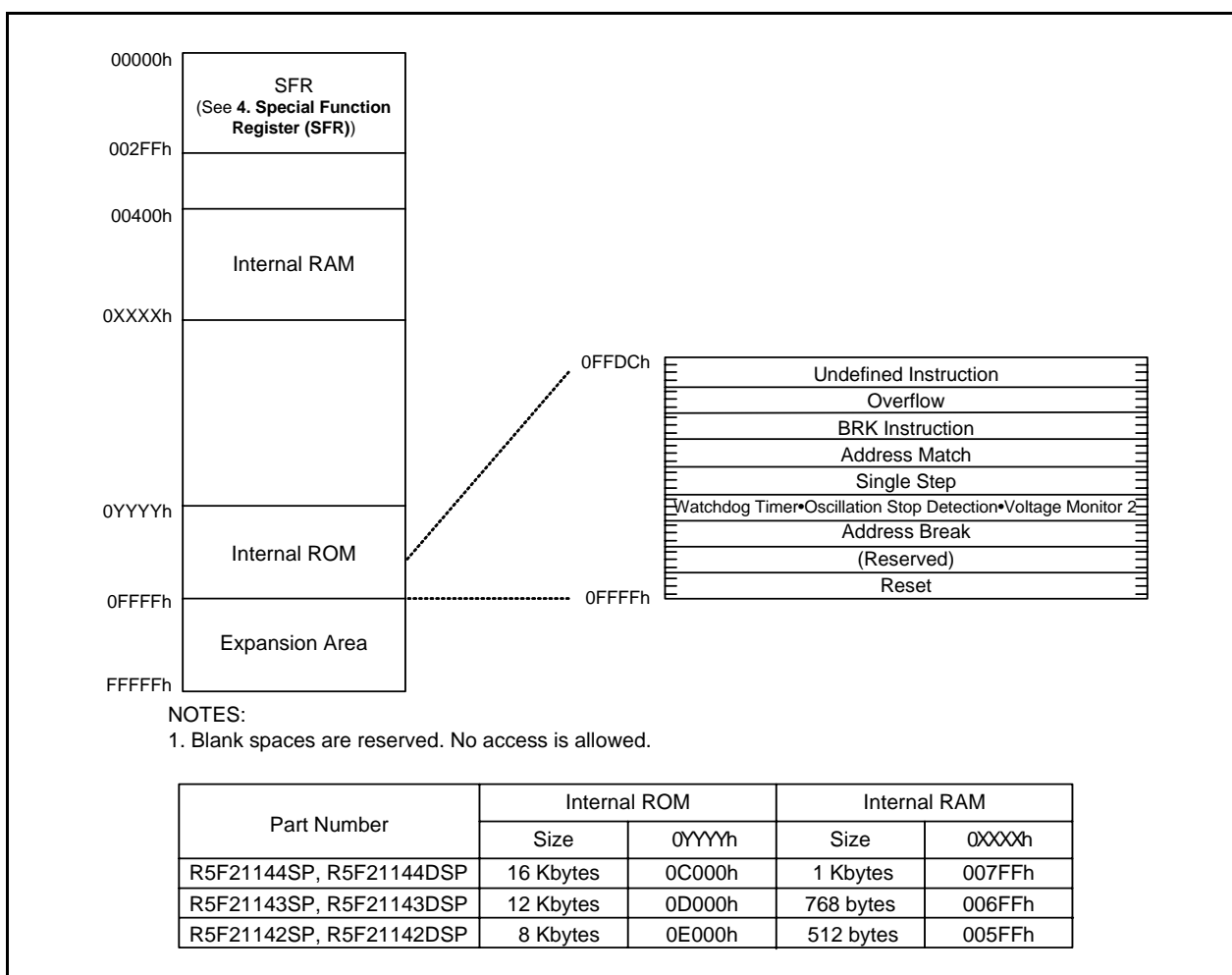
Figure 3.1 is a Memory Map of R8C/14 Group. The R8C/14 group provides 1-Mbyte address space from addresses 00000h to FFFFFh.

The internal ROM is allocated lower addresses beginning with address 0C000h. For example, a 16-Kbyte internal ROM is allocated addresses 0C000h to 0FFFFh.

The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. They store the starting address of each interrupt routine.

The internal RAM is allocated higher addresses beginning with address 00400h. For example, a 1-Kbyte internal RAM is allocated addresses 00400h to 007FFh. The internal RAM is used not only for storing data but for calling subroutines and stacks when interrupt request is acknowledged.

Special function registers (SFR) are allocated addresses 00000h to 002FFh. The peripheral function control registers are allocated them. All addresses, which have nothing allocated within the SFR, are reserved area and cannot be accessed by users.



**Figure 3.1 Memory Map of R8C/14 Group**

### 3.2 R8C/15 Group

Figure 3.2 is a Memory Map of R8C/15 Group. The R8C/15 group provides 1-Mbyte address space from addresses 00000h to FFFFFh.

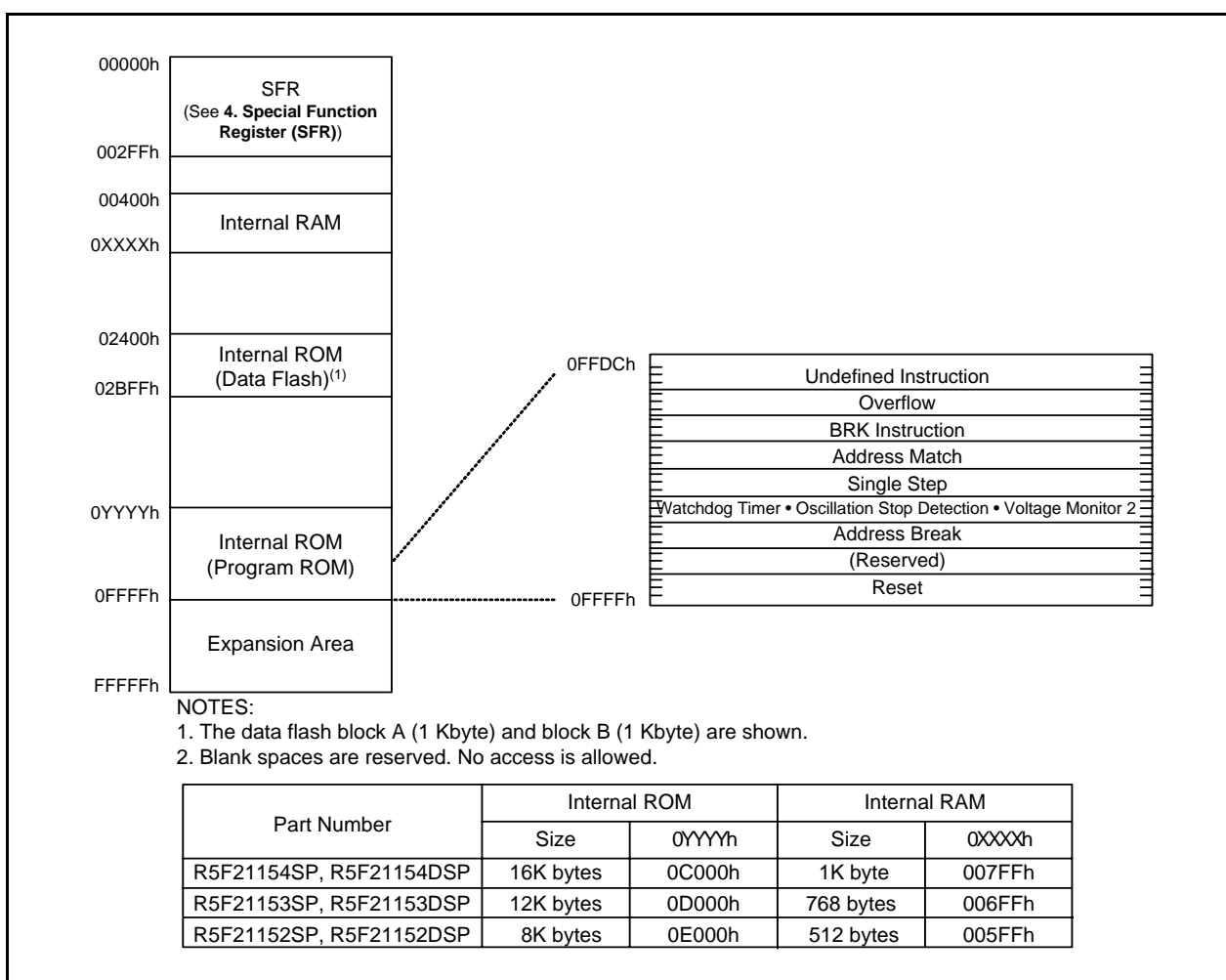
The internal ROM (program ROM) is allocated lower addresses beginning with address 0FFFFh. For example, a 16-Kbyte internal ROM is allocated addresses 0C000h to 0FFFFh.

The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. They store the starting address of each interrupt routine.

The internal ROM (data flash) is allocated addresses 02400h to 02BFFh.

The internal RAM is allocated higher addresses beginning with address 00400h. For example, a 1-Kbyte internal RAM is allocated addresses 00400h to 007FFh. The internal RAM is used not only for storing data but for calling subroutines and stacks when interrupt request is acknowledged.

Special function registers (SFR) are allocated addresses 00000h to 002FFh. The peripheral function control registers are allocated them. All addresses, which have nothing allocated within the SFR, are reserved area and cannot be accessed by users.



**Figure 3.2 Memory Map of R8C/15 Group**

## 4. Special Function Register (SFR)

SFR (Special Function Register) is the control register of peripheral functions. Tables 4.1 to 4.4 list the SFR information.

**Table 4.1 SFR Information(1)(1)**

Address	Register	Symbol	After reset
0000h			
0001h			
0002h			
0003h			
0004h	Processor Mode Register 0	PM0	00h
0005h	Processor Mode Register 1	PM1	00h
0006h	System Clock Control Register 0	CM0	01101000b
0007h	System Clock Control Register 1	CM1	00100000b
0008h			
0009h	Address Match Interrupt Enable Register	AIER	00h
000Ah	Protect Register	PRCR	00h
000Bh			
000Ch	Oscillation Stop Detection Register	OSD	00000100b
000Dh	Watchdog Timer Reset Register	WDTR	XXh
000Eh	Watchdog Timer Start Register	WDTS	XXh
000Fh	Watchdog Timer Control Register	WDC	00011111b
0010h	Address Match Interrupt Register 0	RMAD0	00h
0011h			00h
0012h			X0h
0013h			
0014h	Address Match Interrupt Register 1	RMAD1	00h
0015h			00h
0016h			X0h
0017h			
0018h			
0019h			
001Ah			
001Bh			
001Ch	Count Source Protection Mode Register	CSPR	00h
001Dh			
001Eh	INT0 Input Filter Select Register	INT0F	00h
001Fh			
0020h	High-Speed On-Chip Oscillator Control Register 0	HRA0	00h
0021h	High-Speed On-Chip Oscillator Control Register 1	HRA1	When shipping
0022h	High-Speed On-Chip Oscillator Control Register 2	HRA2	00h
0023h			
0024h			
0025h			
0026h			
0027h			
0028h			
0029h			
002Ah			
002Bh			
002Ch			
002Dh			
002Eh			
002Fh			
0030h			
0031h	Voltage Detection Register 1 <sup>(2)</sup>	VCA1	00001000b
0032h	Voltage Detection Register 2 <sup>(2)</sup>	VCA2	00h <sup>(3)</sup> 01000000b <sup>(4)</sup>
0033h			
0034h			
0035h			
0036h	Voltage Monitor 1 Circuit Control Register <sup>(2)</sup>	VW1C	0000X000b <sup>(3)</sup> 0100X001b <sup>(4)</sup>
0037h	Voltage Monitor 2 Circuit Control Register <sup>(5)</sup>	VW2C	00h
0038h			
0039h			
003Ah			
003Bh			
003Ch			
003Dh			
003Eh			
003Fh			

X: Undefined

**NOTES:**

- Blank spaces are reserved. No access is allowed.
- Software reset, the watchdog timer reset or the voltage monitor 2 reset does not affect this register.
- Owing to Hardware reset.
- Owing to Power-on reset or the voltage monitor 1 reset.
- Software reset, the watchdog timer reset or the voltage monitor 2 reset does not affect the b2 and b3.

**Table 4.2 SFR Information(2)(1)**

Address	Register	Symbol	After reset
0040h			
0041h			
0042h			
0043h			
0044h			
0045h			
0046h			
0047h			
0048h			
0049h			
004Ah			
004Bh			
004Ch			
004Dh	Key Input Interrupt Control Register	KUPIC	XXXXX000b
004Eh	A/D Conversion Interrupt Control Register	ADIC	XXXXX000b
004Fh	SSU Interrupt Control Register	SSUAIC	XXXXX000b
0050h	Compare 1 Interrupt Control Register	CMP1IC	XXXXX000b
0051h	UART0 Transmit Interrupt Control Register	S0TIC	XXXXX000b
0052h	UART0 Receive Interrupt Control Register	S0RIC	XXXXX000b
0053h			
0054h			
0055h			
0056h	Timer X Interrupt Control Register	TXIC	XXXXX000b
0057h			
0058h	Timer Z Interrupt Control Register	TZIC	XXXXX000b
0059h	INT1 Interrupt Control Register	INT1IC	XXXXX000b
005Ah	INT3 Interrupt Control Register	INT3IC	XXXXX000b
005Bh	Timer C Interrupt Control Register	TCIC	XXXXX000b
005Ch	Compare 0 Interrupt Control Register	CMP0IC	XXXXX000b
005Dh	INT0 Interrupt Control Register	INT0IC	XX00X000b
005Eh			
005Fh			
0060h			
0061h			
0062h			
0063h			
0064h			
0065h			
0066h			
0067h			
0068h			
0069h			
006Ah			
006Bh			
006Ch			
006Dh			
006Eh			
006Fh			
0070h			
0071h			
0072h			
0073h			
0074h			
0075h			
0076h			
0077h			
0078h			
0079h			
007Ah			
007Bh			
007Ch			
007Dh			
007Eh			
007Fh			

X: Undefined

## NOTES:

- Blank spaces are reserved. No access is allowed.

**Table 4.4 SFR Information(4)(1)**

Address	Register	Symbol	After reset
00C0h	A/D Register	AD	XXh
00C1h			XXh
00C2h			
00C3h			
00C4h			
00C5h			
00C6h			
00C7h			
00C8h			
00C9h			
00CAh			
00CBh			
00CCh			
00CDh			
00CEh			
00CFh			
00D0h			
00D1h			
00D2h			
00D3h			
00D4h	A/D Control Register 2	ADCON2	00h
00D5h			
00D6h	A/D Control Register 0	ADCON0	00000XXXb
00D7h	A/D Control Register 1	ADCON1	00h
00D8h			
00D9h			
00DAh			
00DBh			
00DCh			
00DDh			
00DEh			
00DFh			
00E0h			
00E1h	Port P1 Register	P1	XXh
00E2h			
00E3h	Port P1 Direction Register	PD1	00h
00E4h			
00E5h	Port P3 Register	P3	XXh
00E6h			
00E7h	Port P3 Direction Register	PD3	00h
00E8h	Port P4 Register	P4	XXh
00E9h			
00EAh	Port P4 Direction Register	PD4	00h
00EBh			
00ECh			
00EDh			
00EEh			
00EFh			
00F0h			
00F1h			
00F2h			
00F3h			
00F4h			
00F5h			
00F6h			
00F7h			
00F8h			
00F9h			
00FAh			
00FBh			
00FCh	Pull-Up Control Register 0	PUR0	00XX0000b
00FDh	Pull-Up Control Register 1	PUR1	XXXXXX0Xb
00FEh	Port P1 Drive Capacity Control Register	DRR	00h
00FFh	Timer C Output Control Register	TCOUT	00h
01B3h	Flash Memory Control Register 4	FMR4	01000000b
01B4h			
01B5h	Flash Memory Control Register 1	FMR1	1000000Xb
01B6h			
01B7h	Flash Memory Control Register 0	FMR0	00000001b
0FFFh	Optional Function Select Register	OFS	(2)

X: Undefined

## NOTES:

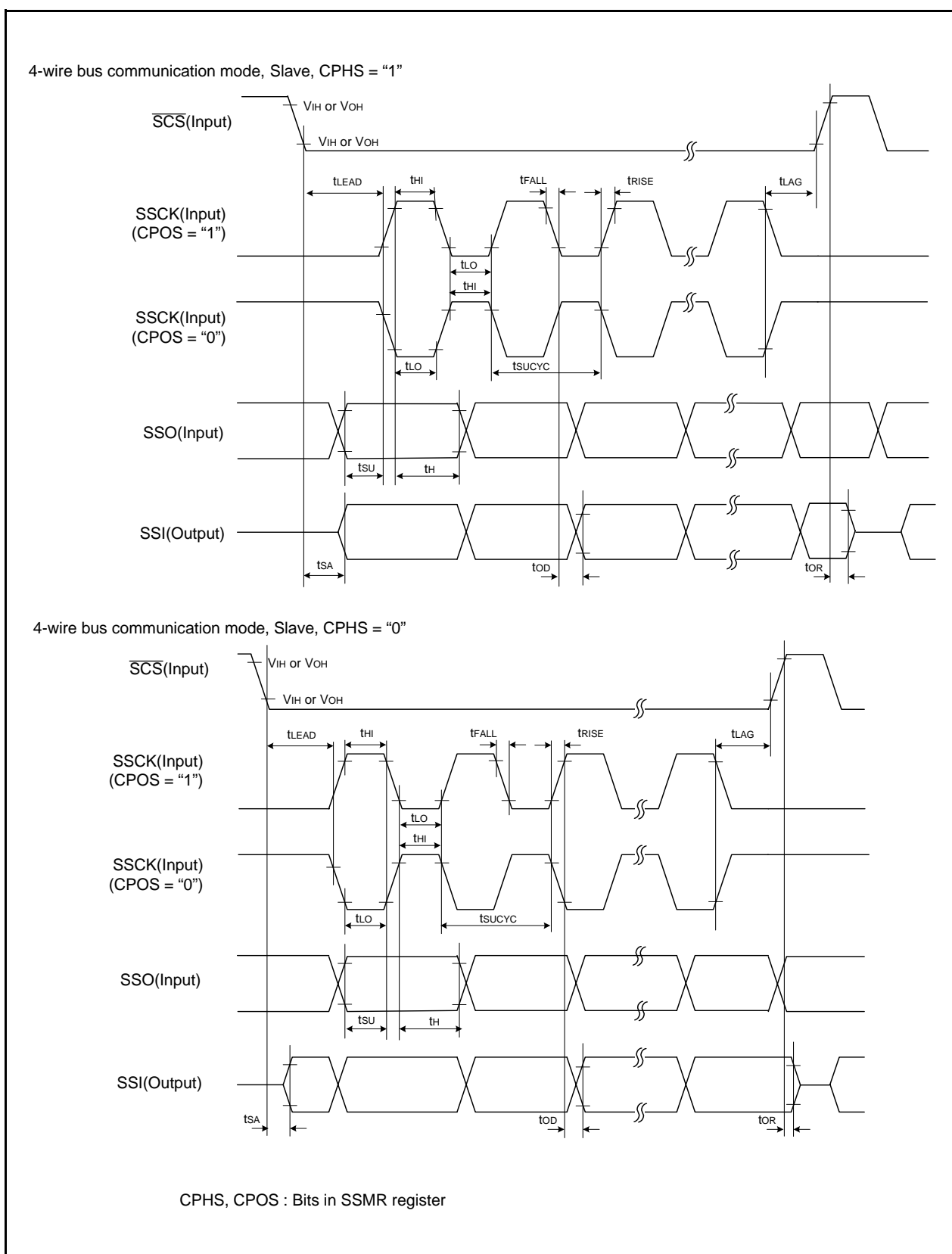
- Blank columns, 0100h to 01B2h and 01B8h to 02FFh are all reserved. No access is allowed.
- The OFS register cannot be changed by program. Use a flash programmer to write to it.

**Table 5.4 Flash Memory (Program ROM) Electrical Characteristics**

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
–	Program/Erase Endurance <sup>(2)</sup>	R8C/14 Group	100 <sup>(3)</sup>	–	–	times
		R8C/15 Group	1,000 <sup>(3)</sup>	–	–	times
–	Byte Program Time	V <sub>CC</sub> = 5.0 V at T <sub>opr</sub> = 25 °C	–	50	400	μs
–	Block Erase Time	V <sub>CC</sub> = 5.0 V at T <sub>opr</sub> = 25 °C	–	0.4	9	s
t <sub>d</sub> (SR-ES)	Time Delay from Suspend Request until Erase Suspend		–	–	8	ms
–	Erase Suspend Request Interval		10	–	–	ms
–	Program, Erase Voltage		2.7	–	5.5	V
–	Read Voltage		2.7	–	5.5	V
–	Program, Erase Temperature		0	–	60	°C
–	Data Hold Time <sup>(7)</sup>	Ambient temperature = 55 °C	20	–	–	year

**NOTES:**

1. V<sub>CC</sub> = AV<sub>CC</sub> = 2.7 to 5.5V at T<sub>opr</sub> = 0 to 60 °C, unless otherwise specified.
2. Definition of program and erase  
The program and erase endurance shows an erase endurance for every block.  
If the program and erase endurance is “n” times (n = 100, 10000), “n” times erase can be performed for every block.  
For example, if performing 1-byte write to the distinct addresses on Block A of 1Kbyte block 1,024 times and then erasing that block, program and erase endurance is counted as one time.  
However, do not perform multiple programs to the same address for one time erase.(disable overwriting).
3. Endurance to guarantee all electrical characteristics after program and erase.(1 to “Min.” value can be guaranteed).
4. In the case of a system to execute multiple programs, perform one erase after programming as reducing effective reprogram endurance not to leave blank area as possible such as programming write addresses in turn . If programming a set of 16 bytes, programming up to 128 sets and then erasing them one time can reduce effective reprogram endurance. Additionally, averaging erase endurance for Block A and B can reduce effective reprogram endurance more. To leave erase endurance for every block as information and determine the restricted endurance are recommended.
5. If error occurs during block erase, attempt to execute the clear status register command, then the block erase command at least three times until the erase error does not occur.
6. Customers desiring Program/Erase failure rate information should contact their Renesas technical support representative.
7. The data hold time includes time that the power supply is off or the clock is not supplied.



**Figure 5.5 I/O Timing of Clock Synchronous Serial I/O (SSU) with Chip Select (Slave)**

**Table 5.14 Electrical Characteristics (2) [Vcc = 5V] (Topr = -40 to 85 °C, unless otherwise specified.)**

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
Icc	Power Supply Current (Vcc=3.3 to 5.5V) In single-chip mode, the output pins are open and other pins are Vss	High-Speed Mode XIN = 20MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on=125kHz No division	–	9	15	mA
			–	8	14	mA
			–	5	–	mA
		Medium-Speed Mode XIN = 20MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on=125kHz Divide-by-8	–	4	–	mA
			–	3	–	mA
			–	2	–	mA
		High-Speed On-Chip Oscillator Mode Main clock off High-speed on-chip oscillator on=8MHz Low-speed on-chip oscillator on=125kHz No division	–	4	8	mA
			–	1.5	–	mA
		Low-Speed On-Chip Oscillator Mode Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on=125kHz Divide-by-8	–	470	900	μA
		Wait Mode Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on=125kHz While a WAIT instruction is executed Peripheral clock operation VCA26 = VCA27 = 0	–	40	80	μA
		Wait Mode Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on=125kHz While a WAIT instruction is executed Peripheral clock off VCA26 = VCA27 = 0	–	38	76	μA
		Stop Mode Main clock off, Topr = 25 °C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA26 = VCA27 = 0	–	0.8	3.0	μA



**Timing Requirements (Unless otherwise specified: V<sub>CC</sub> = 5V, V<sub>SS</sub> = 0V at Topr = 25 °C) [ V<sub>CC</sub> = 5V ]****Table 5.15 XIN Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
t <sub>c</sub> (XIN)	XIN Input Cycle Time	50	–	ns
t <sub>WH</sub> (XIN)	XIN Input “H” Width	25	–	ns
t <sub>WL</sub> (XIN)	XIN Input “L” Width	25	–	ns

**Table 5.16 CNTR0 Input, CNTR1 Input,  $\overline{\text{INT1}}$  Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
t <sub>c</sub> (CNTR0)	CNTR0 Input Cycle Time	100	–	ns
t <sub>WH</sub> (CNTR0)	CNTR0 Input “H” Width	40	–	ns
t <sub>WL</sub> (CNTR0)	CNTR0 input “L” Width	40	–	ns

**Table 5.17 TCIN Input,  $\overline{\text{INT3}}$  Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
t <sub>c</sub> (TCIN)	TCIN Input Cycle Time	400 <sup>(1)</sup>	–	ns
t <sub>WH</sub> (TCIN)	TCIN Input “H” Width	200 <sup>(2)</sup>	–	ns
t <sub>WL</sub> (TCIN)	TCIN input “L” Width	200 <sup>(2)</sup>	–	ns

**NOTES:**

1. When using Timer C input capture mode, adjust the cycle time ( 1/Timer C count source frequency x 3) or above.
2. When using Timer C input capture mode, adjust the width ( 1/Timer C count source frequency x 1.5) or above.

**Table 5.18 Serial Interface**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
t <sub>c</sub> (CK)	CLKi Input Cycle Time	200	–	ns
t <sub>w</sub> (CKH)	CLKi Input “H” Width	100	–	ns
t <sub>w</sub> (CKL)	CLKi Input “L” Width	100	–	ns
t <sub>d</sub> (C-Q)	TXDi Output Delay Time	–	50	ns
t <sub>h</sub> (C-Q)	TXDi Hold Time	0	–	ns
t <sub>su</sub> (D-C)	RXDi Input Setup Time	50	–	ns
t <sub>h</sub> (C-D)	RCDi Input Hold Time	90	–	ns

**Table 5.19 External Interrupt  $\overline{\text{INT0}}$  Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
t <sub>w</sub> (INH)	$\overline{\text{INT0}}$ Input “H” Width	250 <sup>(1)</sup>	–	ns
t <sub>w</sub> (INL)	$\overline{\text{INT0}}$ Input “L” Width	250 <sup>(2)</sup>	–	ns

**NOTES:**

1. When selecting the digital filter by the  $\overline{\text{INT0}}$  input filter select bit, use the  $\overline{\text{INT0}}$  input HIGH width to the greater value, either (1/digital filter clock frequency x 3) or the minimum value of standard.
2. When selecting the digital filter by the  $\overline{\text{INT0}}$  input filter select bit, use the  $\overline{\text{INT0}}$  input LOW width to the greater value, either (1/digital filter clock frequency x 3) or the minimum value of standard.

**Table 5.21 Electrical Characteristics (4) [Vcc = 3V] (Topr = -40 to 85 °C, unless otherwise specified.)**

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
Icc	Power Supply Current (Vcc=2.7 to 3.3V) In single-chip mode, the output pins are open and other pins are Vss	High-Speed Mode XIN = 20MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on=125kHz No division	–	8	13	mA
			–	7	12	mA
			–	5	–	mA
		Medium-Speed Mode XIN = 20MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on=125kHz Divide-by-8	–	3	–	mA
			–	2.5	–	mA
			–	1.6	–	mA
		High-Speed On-Chip Oscillator Mode Main clock off High-speed on-chip oscillator on=8MHz Low-speed on-chip oscillator on=125kHz No division	–	3.5	7.5	mA
			–	1.5	–	mA
		Low-Speed On-Chip Oscillator Mode Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on=125kHz Divide-by-8	–	420	800	μA
		Wait Mode Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on=125kHz While a WAIT instruction is executed Peripheral clock operation VCA26 = VCA27 = 0	–	37	74	μA
		Wait Mode Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on=125kHz While a WAIT instruction is executed Peripheral clock off VCA26 = VCA27 = 0	–	35	70	μA
		Stop Mode Main clock off, Topr = 25 °C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA26 = VCA27 = 0	–	0.7	3.0	μA

**Timing requirements (Unless otherwise specified: Vcc = 3V, Vss = 0V at Topr = 25 °C) [Vcc = 3V]****Table 5.22 XIN Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
t <sub>c</sub> (XIN)	XIN Input Cycle Time	100	–	ns
t <sub>WH</sub> (XIN)	XIN Input “H” Width	40	–	ns
t <sub>WL</sub> (XIN)	XIN Input “L” Width	40	–	ns

**Table 5.23 CNTR0 Input, CNTR1 Input,  $\overline{\text{INT1}}$  Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
t <sub>c</sub> (CNTR0)	CNTR0 Input Cycle Time	300	–	ns
t <sub>WH</sub> (CNTR0)	CNTR0 Input “H” Width	120	–	ns
t <sub>WL</sub> (CNTR0)	CNTR0 Input “L” Width	120	–	ns

**Table 5.24 TCIN Input,  $\overline{\text{INT3}}$  Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
t <sub>c</sub> (TCIN)	TCIN Input Cycle Time	1,200 <sup>(1)</sup>	–	ns
t <sub>WH</sub> (TCIN)	TCIN Input “H” Width	600 <sup>(2)</sup>	–	ns
t <sub>WL</sub> (TCIN)	TCIN Input “L” Width	600 <sup>(2)</sup>	–	ns

**NOTES:**

1. When using the Timer C input capture mode, adjust the cycle time (1/Timer C count source frequency x 3) or above.
2. When using the Timer C input capture mode, adjust the width (1/Timer C count source frequency x 1.5) or above.

**Table 5.25 Serial Interface**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
t <sub>c</sub> (CK)	CLKi Input Cycle Time	300	–	ns
t <sub>w</sub> (CKH)	CLKi Input “H” Width	150	–	ns
t <sub>w</sub> (CKL)	CLKi Input “L” Width	150	–	ns
t <sub>d</sub> (C-Q)	TXDi Output Delay Time	–	80	ns
t <sub>h</sub> (C-Q)	TXDi Hold Time	0	–	ns
t <sub>su</sub> (D-C)	RXDi Input Setup Time	70	–	ns
t <sub>h</sub> (C-D)	RCDi Input Hold Time	90	–	ns

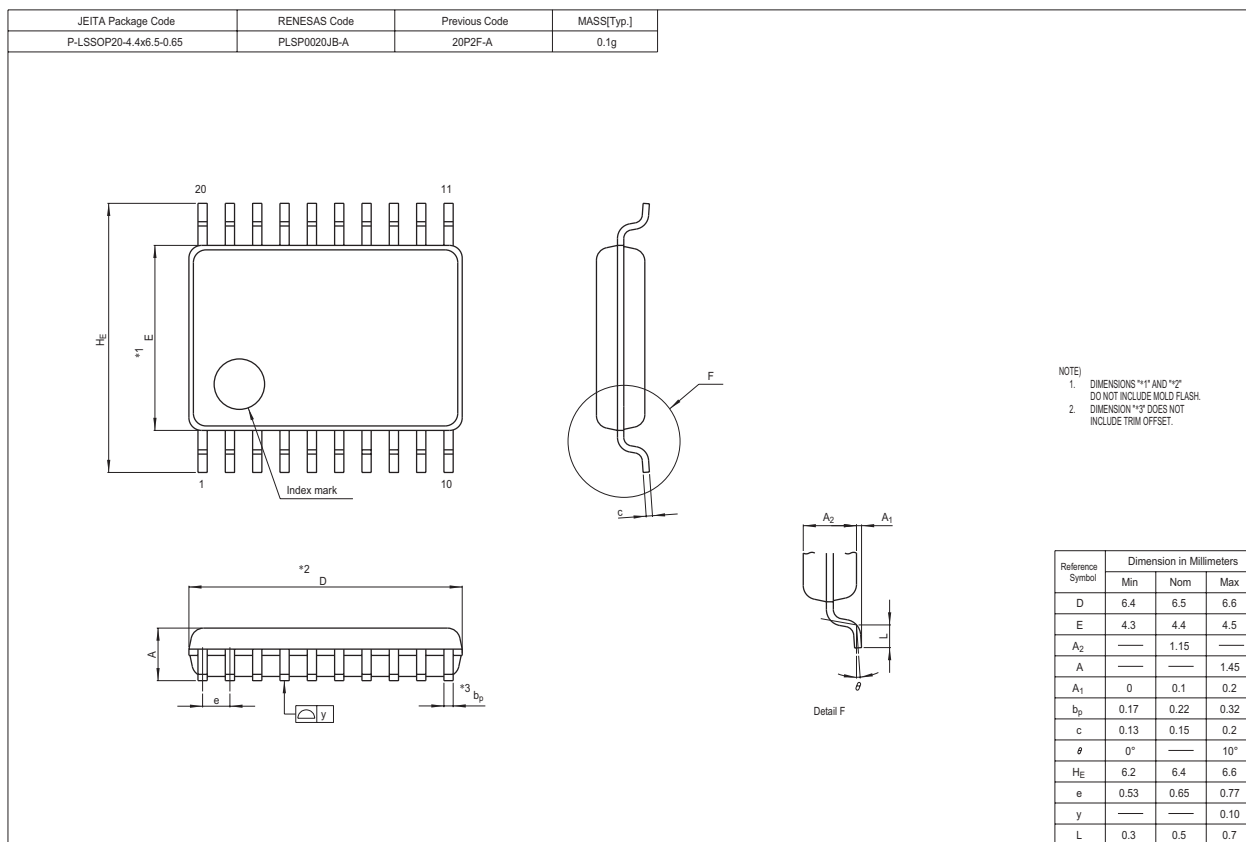
**Table 5.26 External Interrupt  $\overline{\text{INT0}}$  Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
t <sub>w</sub> (INH)	$\overline{\text{INT0}}$ Input “H” Width	380 <sup>(1)</sup>	–	ns
t <sub>w</sub> (INL)	$\overline{\text{INT0}}$ Input “L” Width	380 <sup>(2)</sup>	–	ns

**NOTES:**

1. When selecting the digital filter by the  $\overline{\text{INT0}}$  input filter select bit, use the  $\overline{\text{INT0}}$  input HIGH width to the greater value, either (1/digital filter clock frequency x 3) or the minimum value of standard.
2. When selecting the digital filter by the  $\overline{\text{INT0}}$  input filter select bit, use the  $\overline{\text{INT0}}$  input LOW width to the greater value, either (1/digital filter clock frequency x 3) or the minimum value of standard.

## Package Dimensions



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